

“A Comparison of Scrub Marks & Contact Resistance Between Cantilever Type and New MEMS Type Probe Cards”

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Probe Card Comparison Criteria

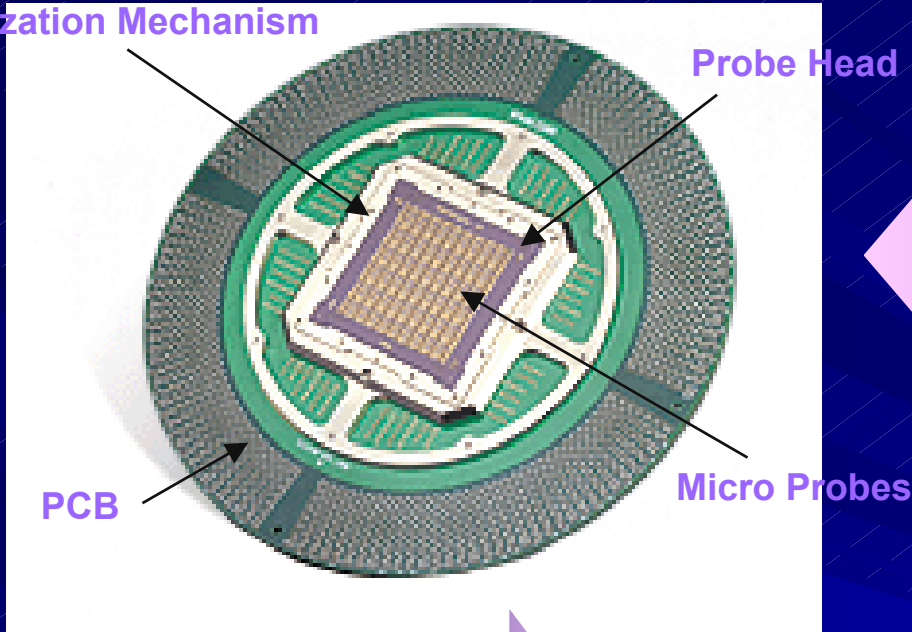
- **1. MEMS PROBE CARD**
- **2. Pin Force**
- **3. Probe Planarity**
- **4. Scrub Mark Width/Depth**
- **5. Probe X,Y Alignment**
- **6. Path Resistance**
- **7. Life Time (Number of touchdowns)**
- **8. Bandwidth**
- **9. Specification**

1. MEMS PROBE CARD

- **Manufactured by MEMS Technology**
- **Vertical Micro Probe**
- **High Multi-DUT**
- **Optional Tip Structure**

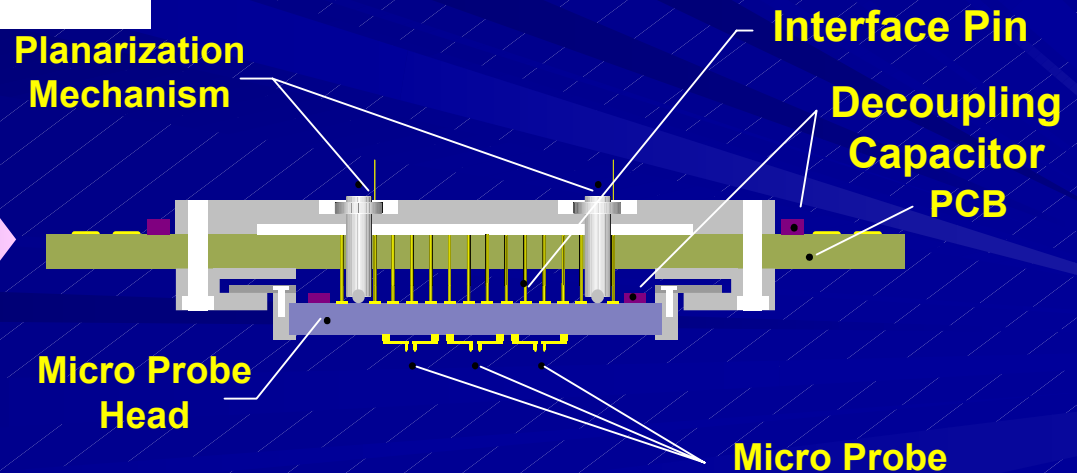
MEMS Probe Card View

Planarization Mechanism

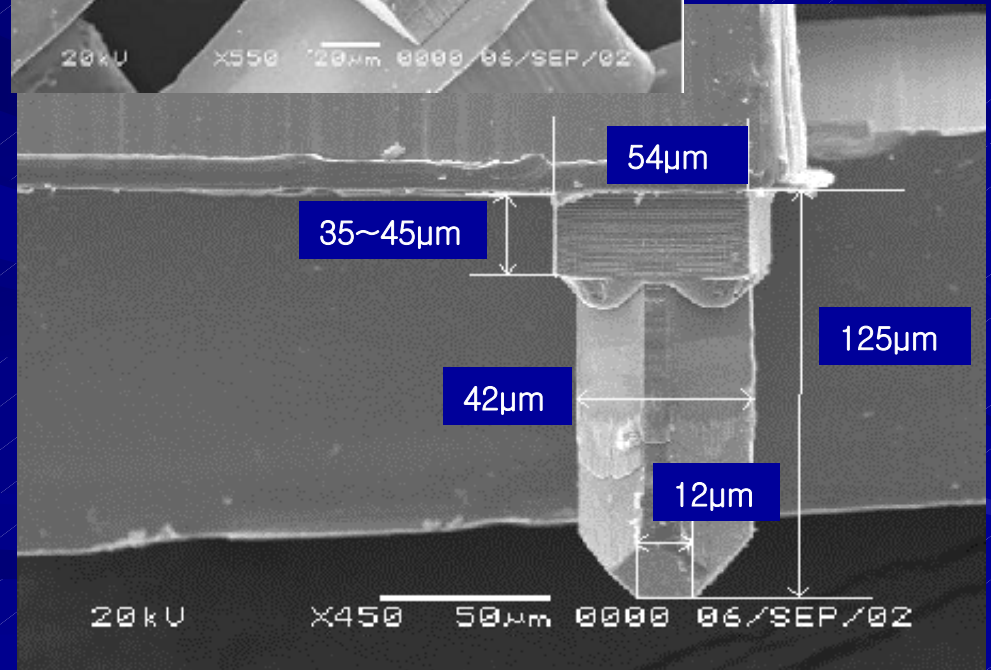
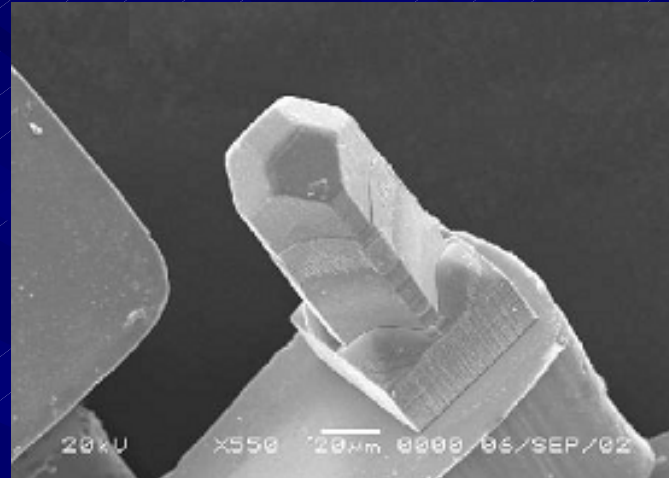
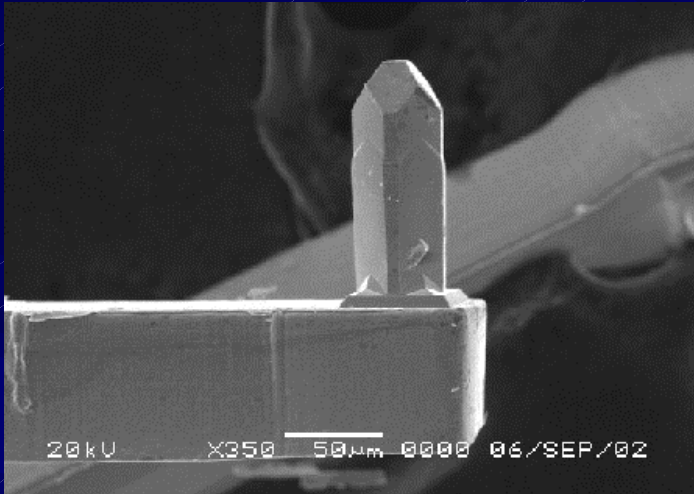


MEMS Probe Card
- Manufactured by MEMS
technology

MEMS Probe Card
side view



Micro Probe Tips of MEMS



MEMS PT1 Type

MEMS PT2 Type

2. Pin Force

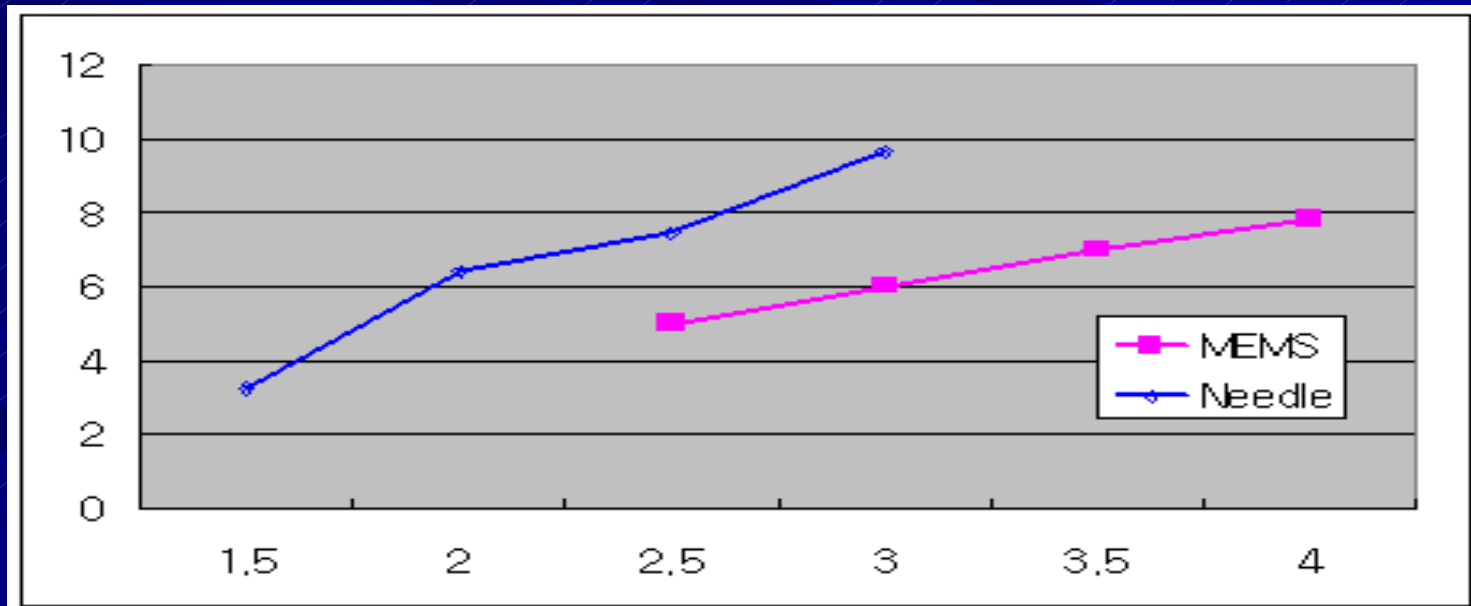
- Overdrive Vs Contact Force

(Unit:gf/mil)

O.D Value	1.5mil	2mil	2.5 mil	3 mil	3.5 mil	4 mil
MEMS P/C	-	-	5.0	6.0	7.0	7.8
Needle P/C	4.6	6.4	7.4	9.7	-	-

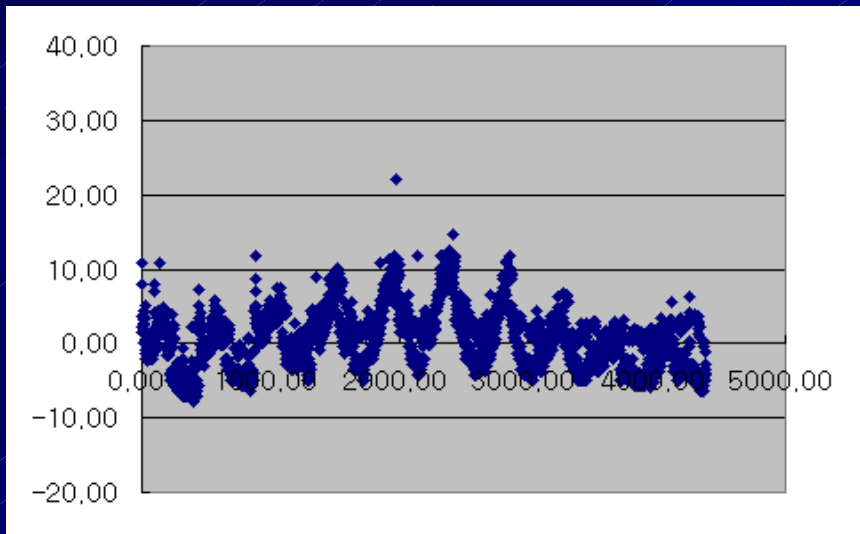
- Graph

(Unit:gf/mil)



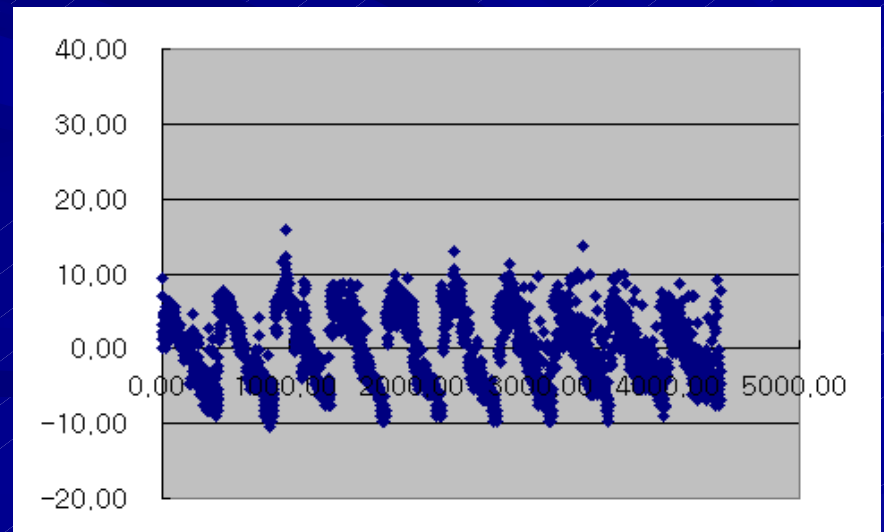
3. Probe Planarity (MEMS P/C 64 DUT)

- The planarity after 29,600 touchdowns
- T/D is real contact number on production line



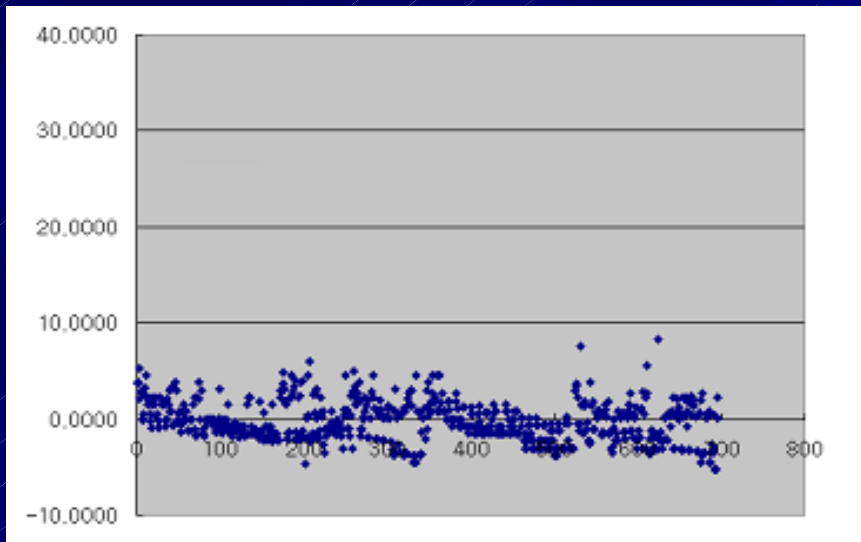
Before TDS

After 29600 TDS (Unit:um)



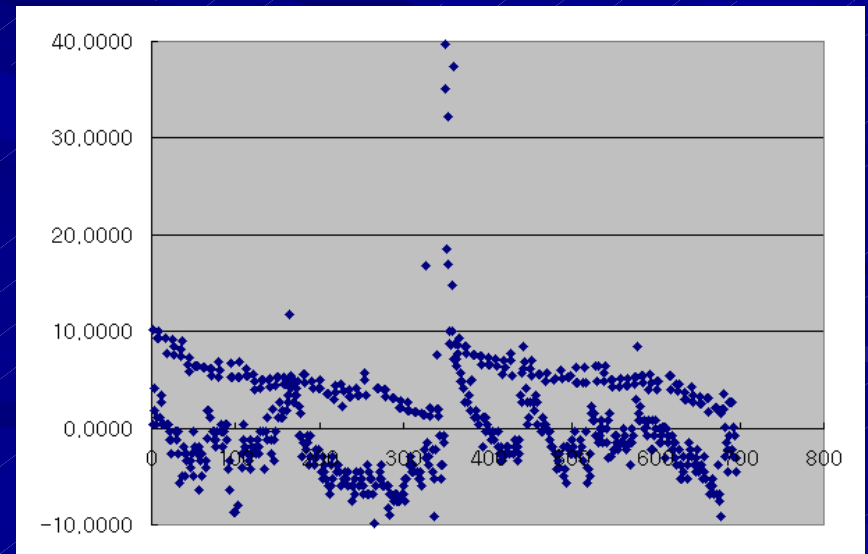
Probe Planarity (NEEDLE TYPE P/C)

- The Planarity after 29,600 Touchdowns
- Touchdown Test in EG 4090 Prober System without Signal



Before TDS

After 29600 TDS (Unit:um)



Probe Planarity (PRVX)

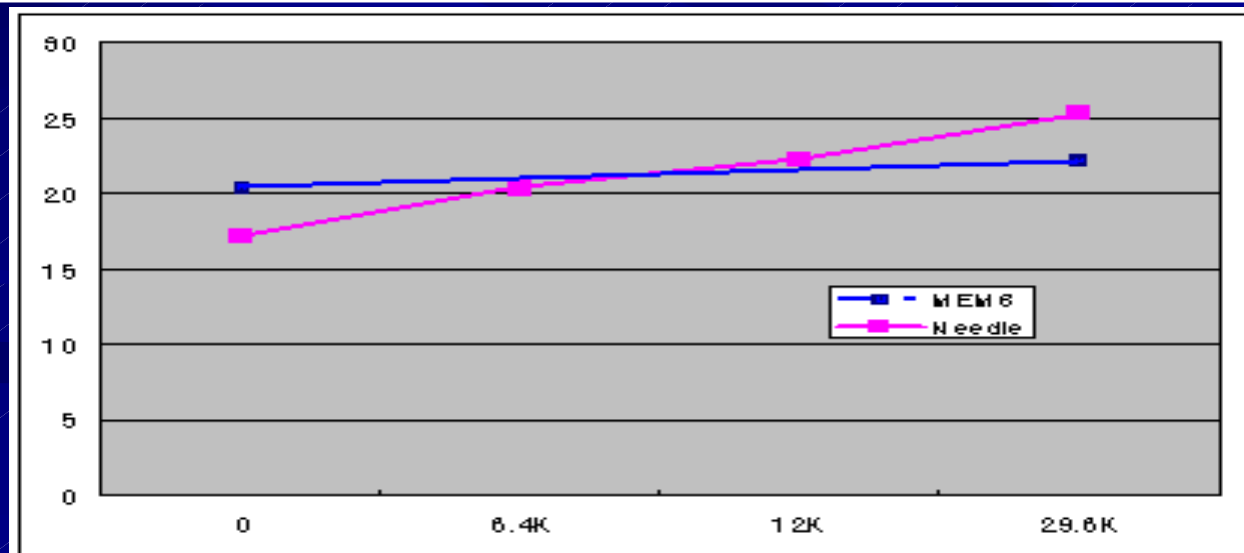
- Touchdowns Vs Planarity (Max.-Min.).

Measure the Pin Planarity after touchdowns

TD of MEMS P/C is real contact number on production line

TD of Needle P/C is internal test data on EG 4090 Prober
(Unit:um)

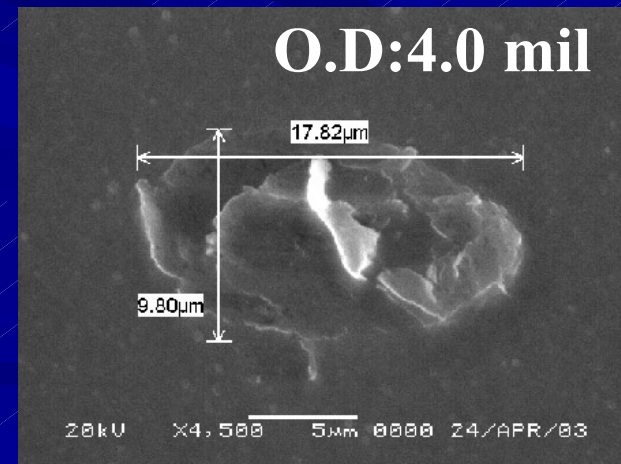
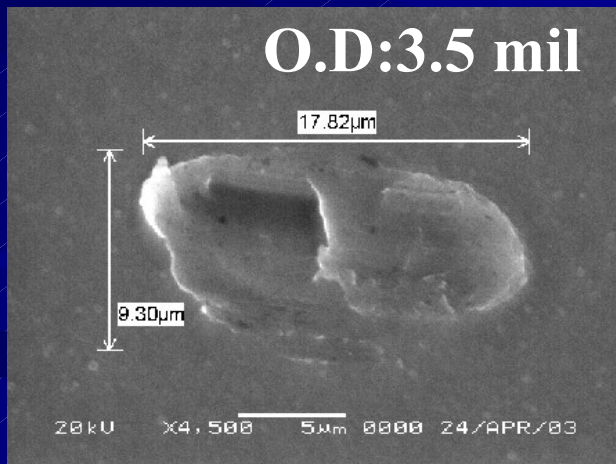
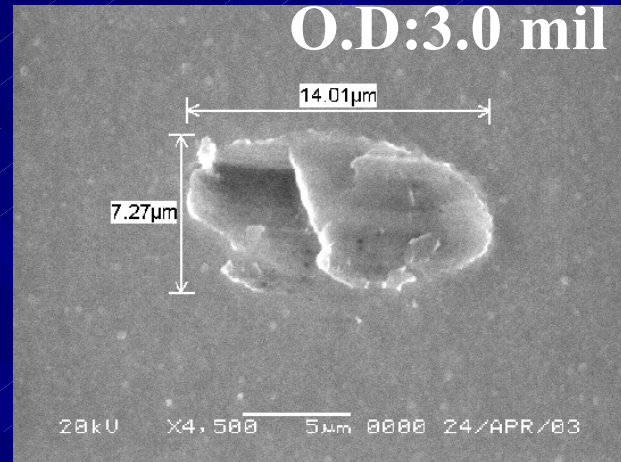
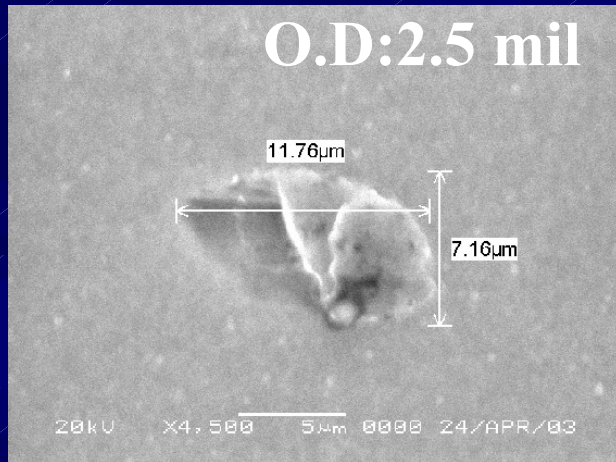
TDS	0	6.4K	12K	29.6K
MEMS P/C	20.3564			22.1466
Needle P/C	17.2214	20.3249	22.2424	25.2181



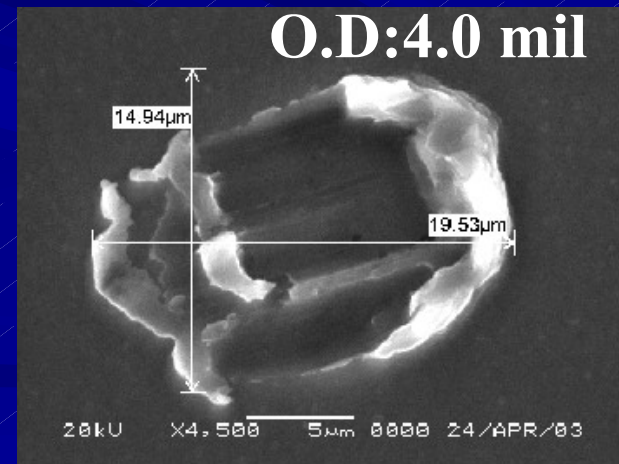
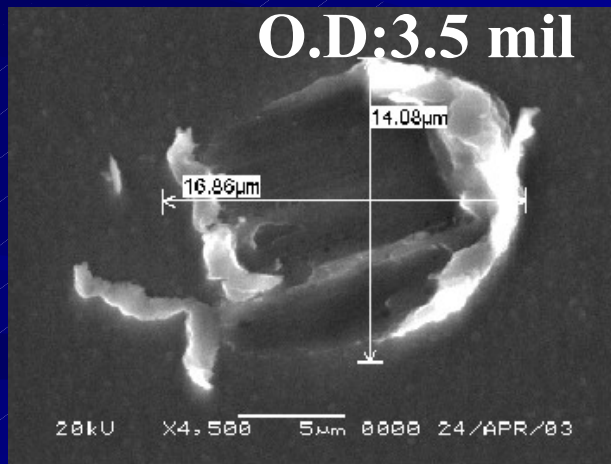
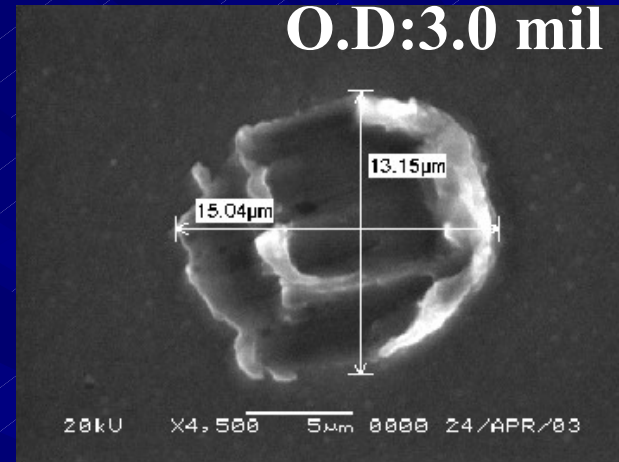
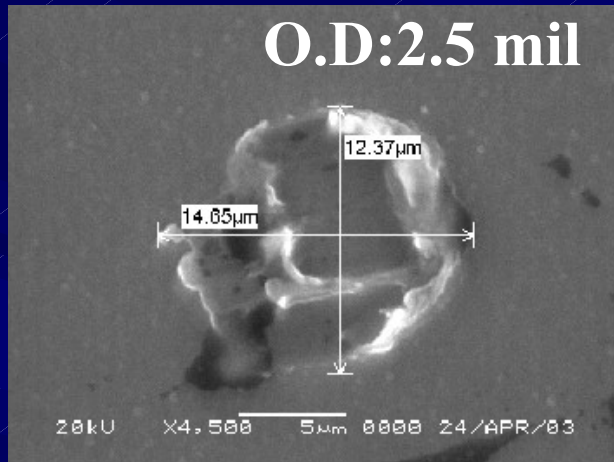
4. Scrub Mark Width/Depth

- PT1 Tip Scrub Mark Width/Depth
- PT2 Tip Scrub Mark Width/Depth
- Needle Scrub Mark Width/Depth

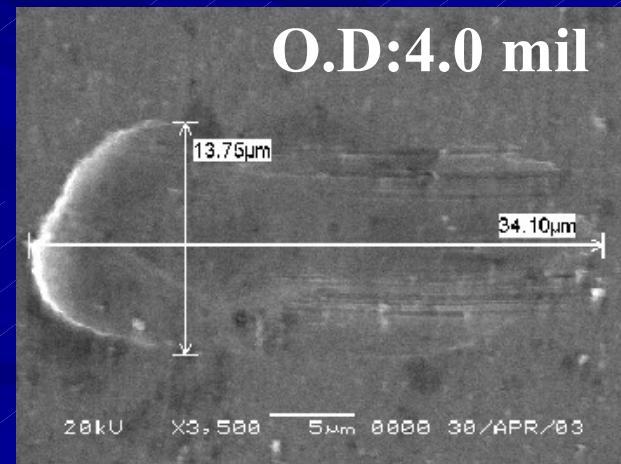
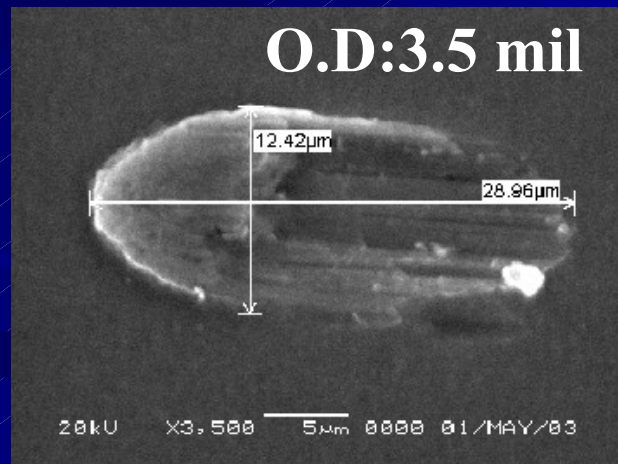
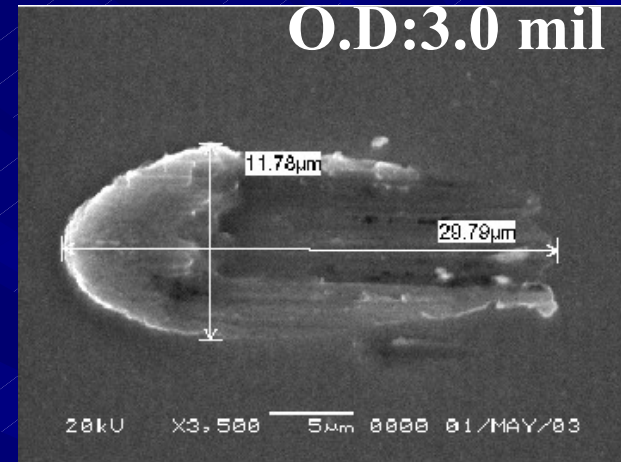
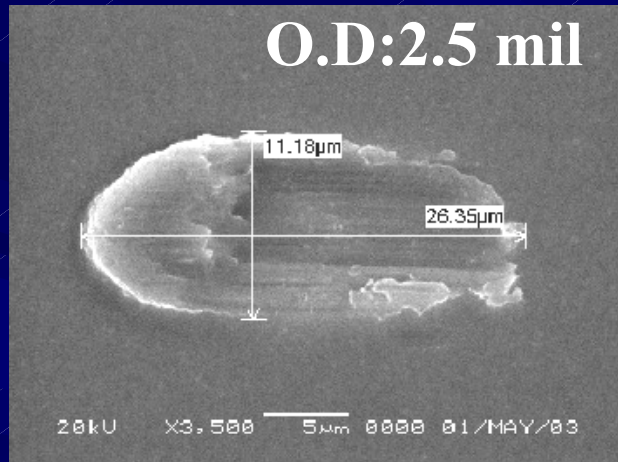
PT1 Tip Scrub Mark Width (SEM)



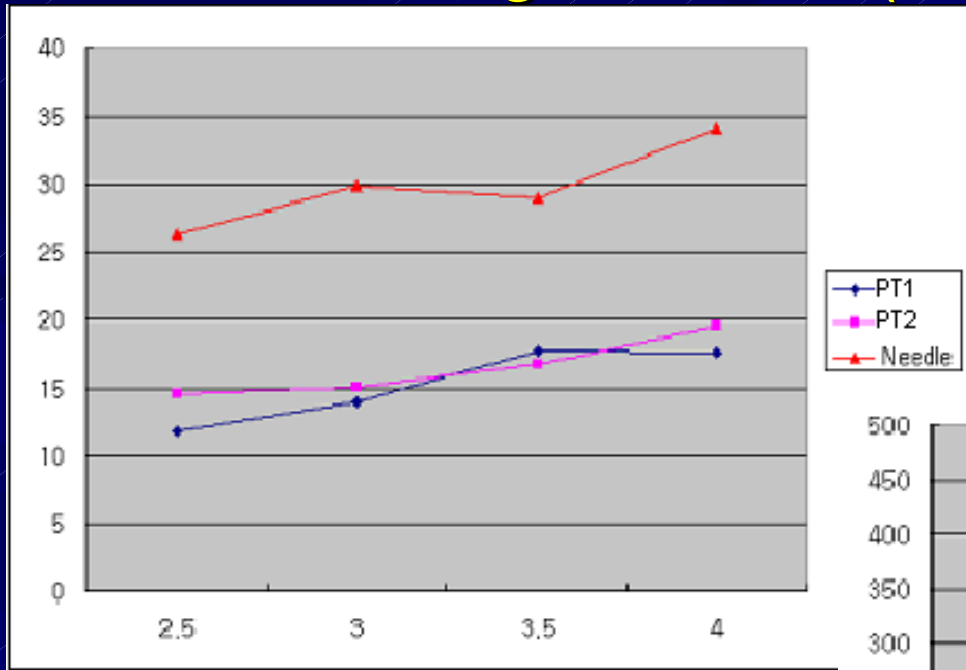
PT2 Tip Scrub Mark Width (SEM)



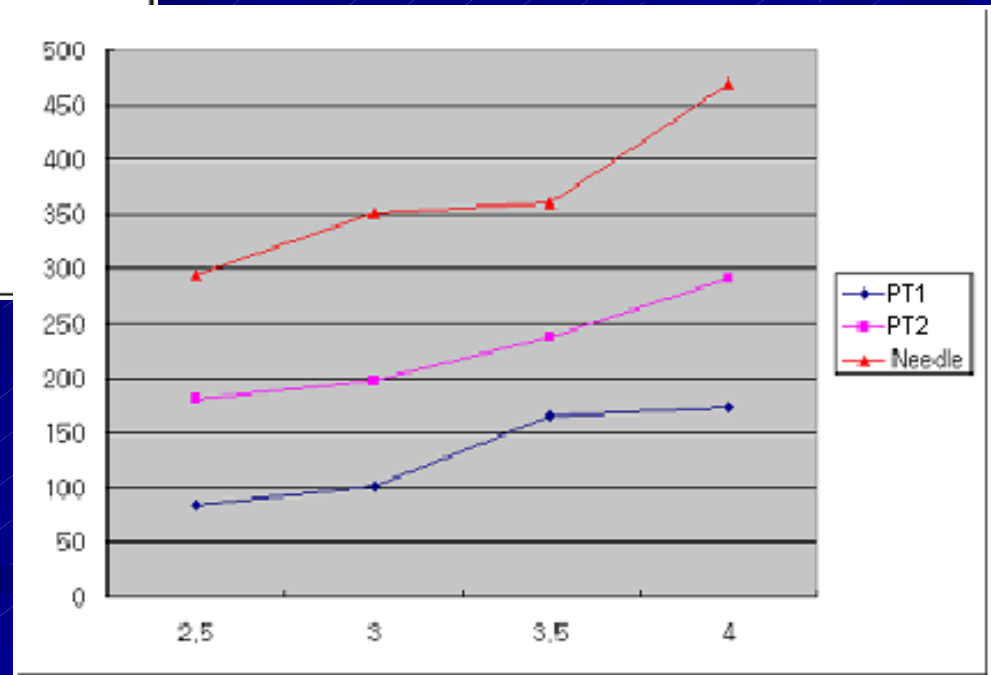
Needle Scrub Mark Width (SEM)



Scrub Length & Area (all types are compared)



Scrub Mark X trend



Scrub Mark X*Y trend

Scrub Mark Depth Measurement Equipment



Model: SIS-1200

Interscan System

Z-Resolution : EPSI 1nm

PSI 0.1nm

Lateral Resolution :MAX0.64um

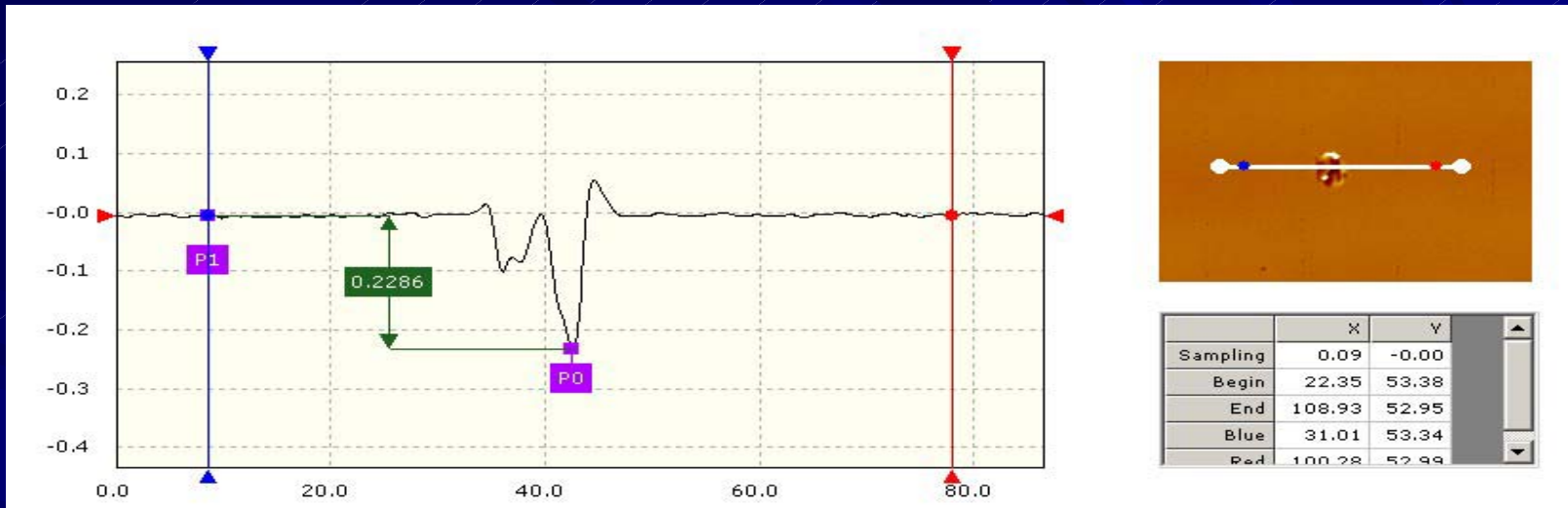
Lens : 50X

L/R:0.64um

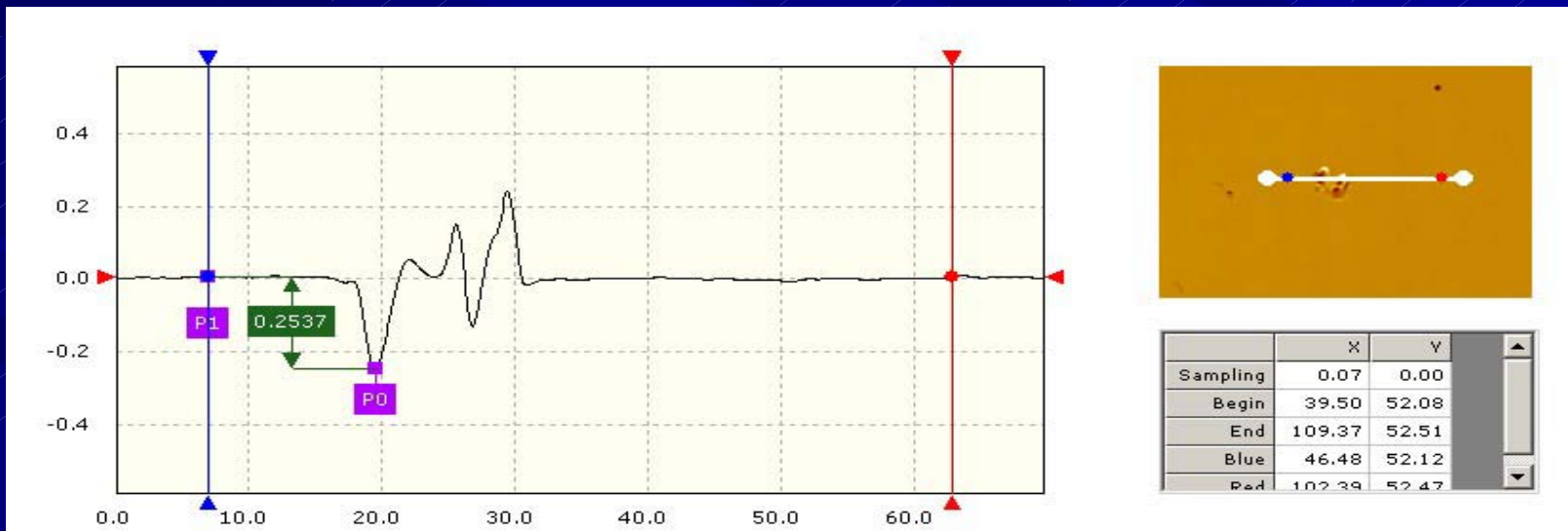
Field of View : 0.14 x 0.10mm

PT1 Tip Scrub Depth

O.D:2.5 mil

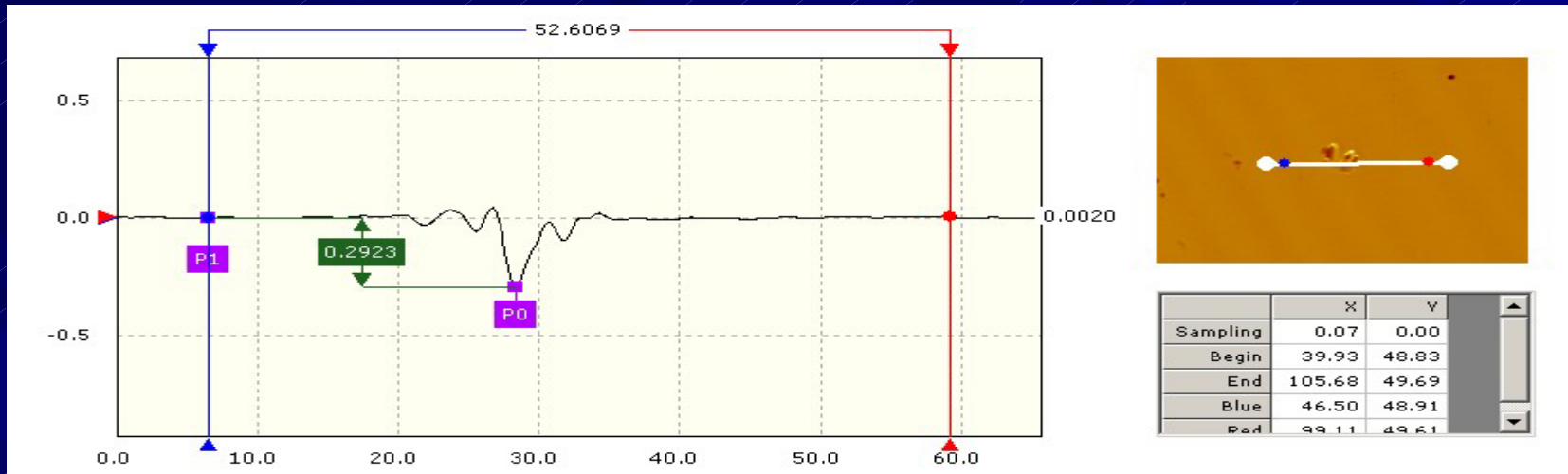


O.D:3.0 mil

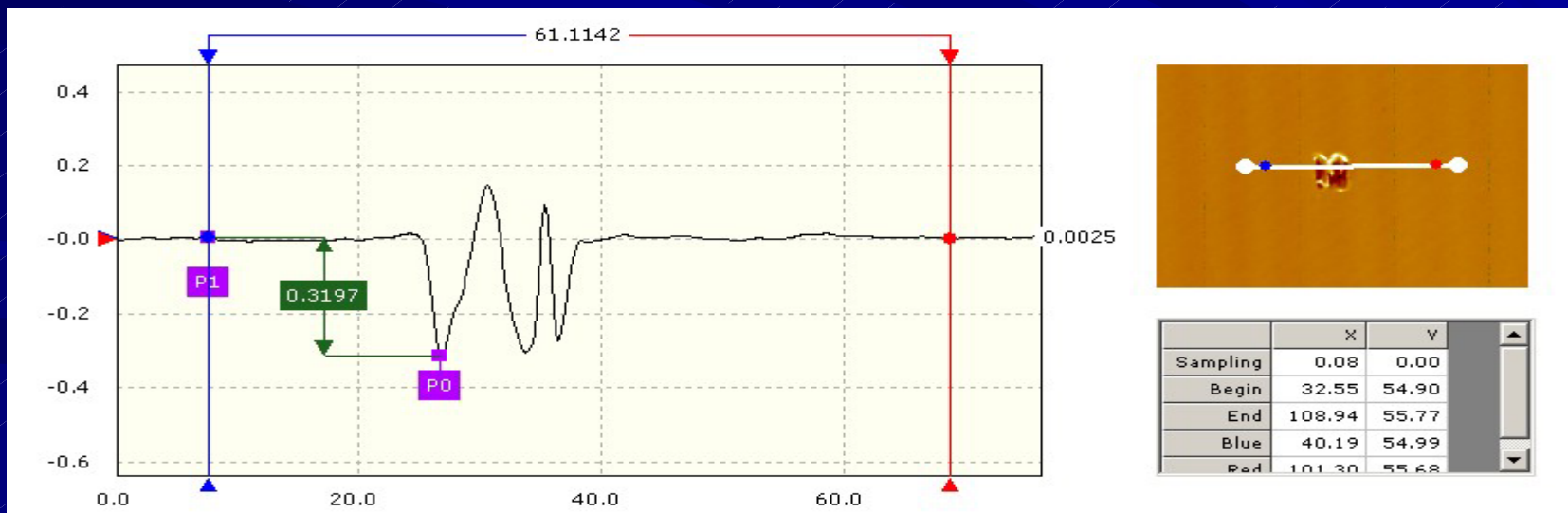


PT1 TIP Scrub Depth

O.D:3.5 mil

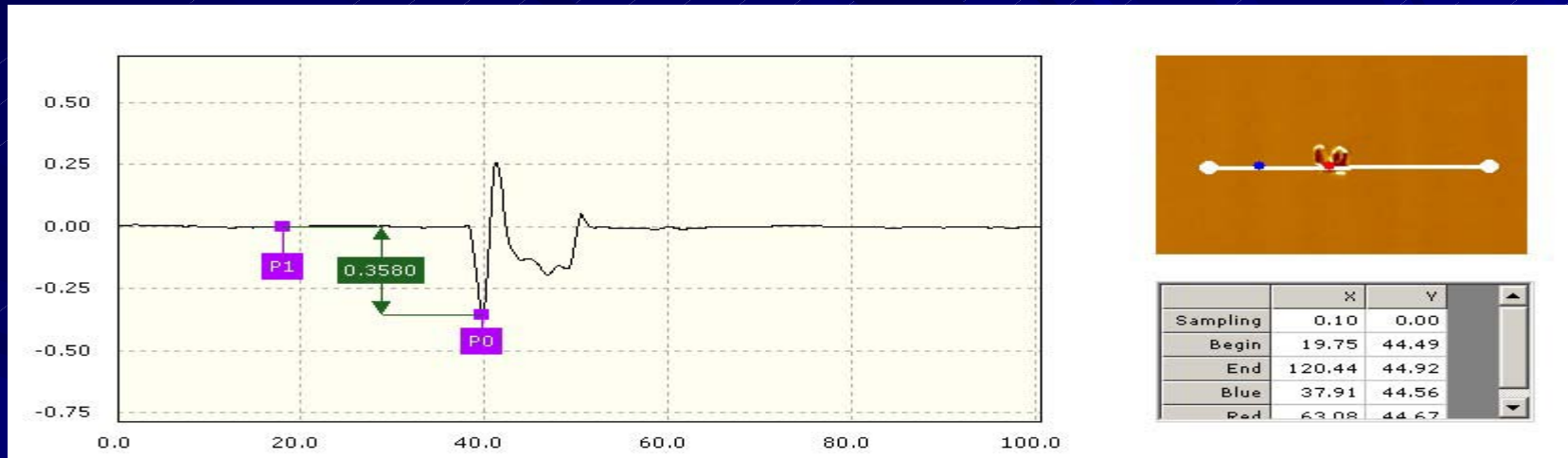


O.D:4.0 mil

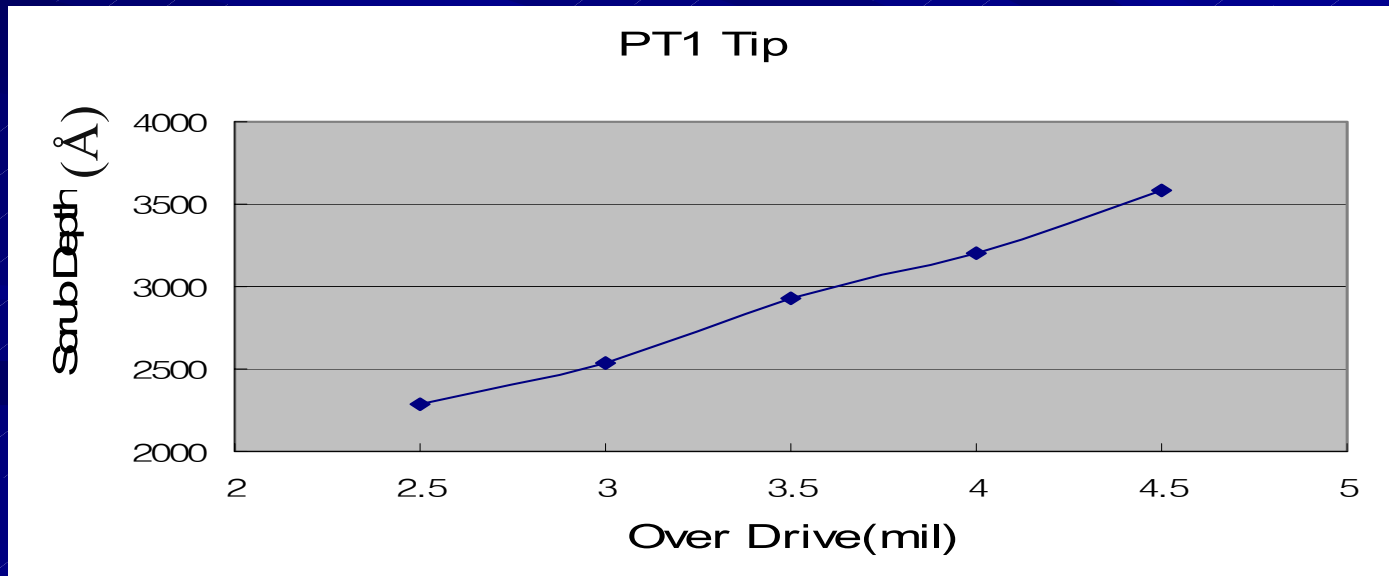


PT1 Tip Scrub Depth

O.D:4.5 mil

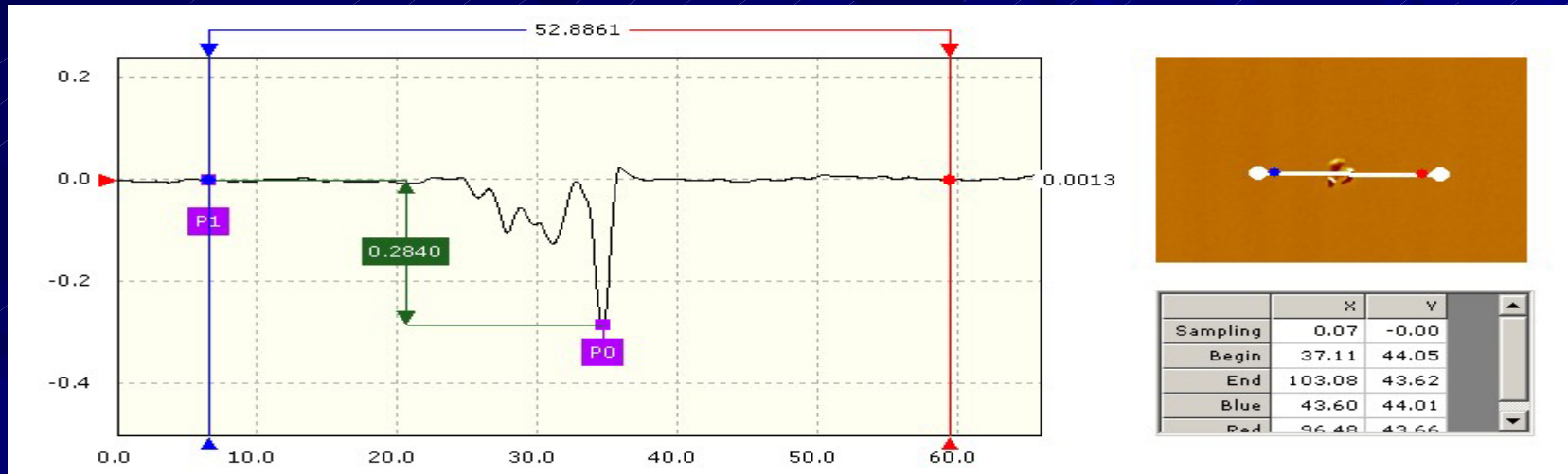


PT1 Tip Scrub Depth Trend

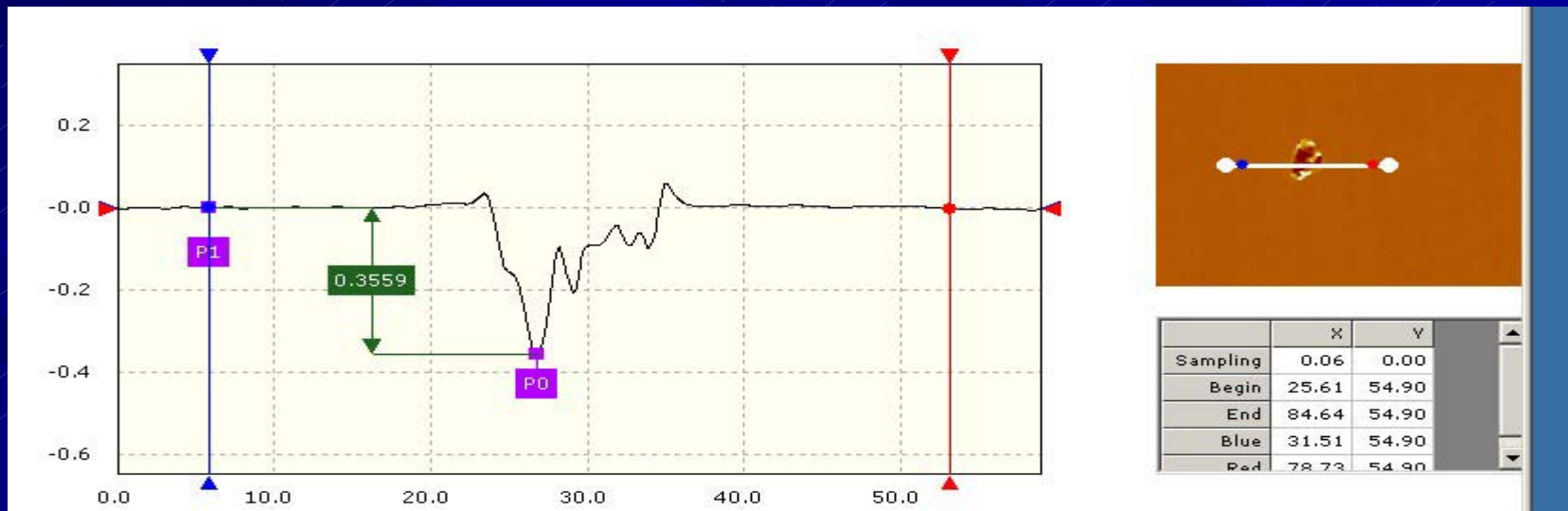


PT2 Tip Scrub Depth

O.D:2.5 mil

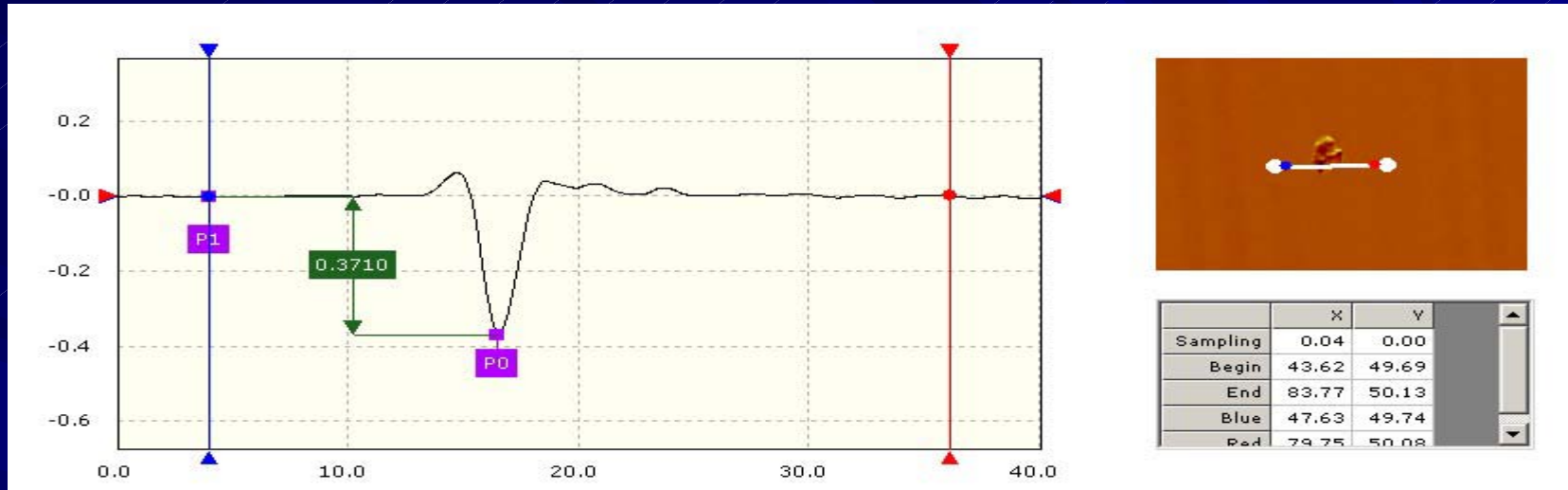


O.D:3.0 mil

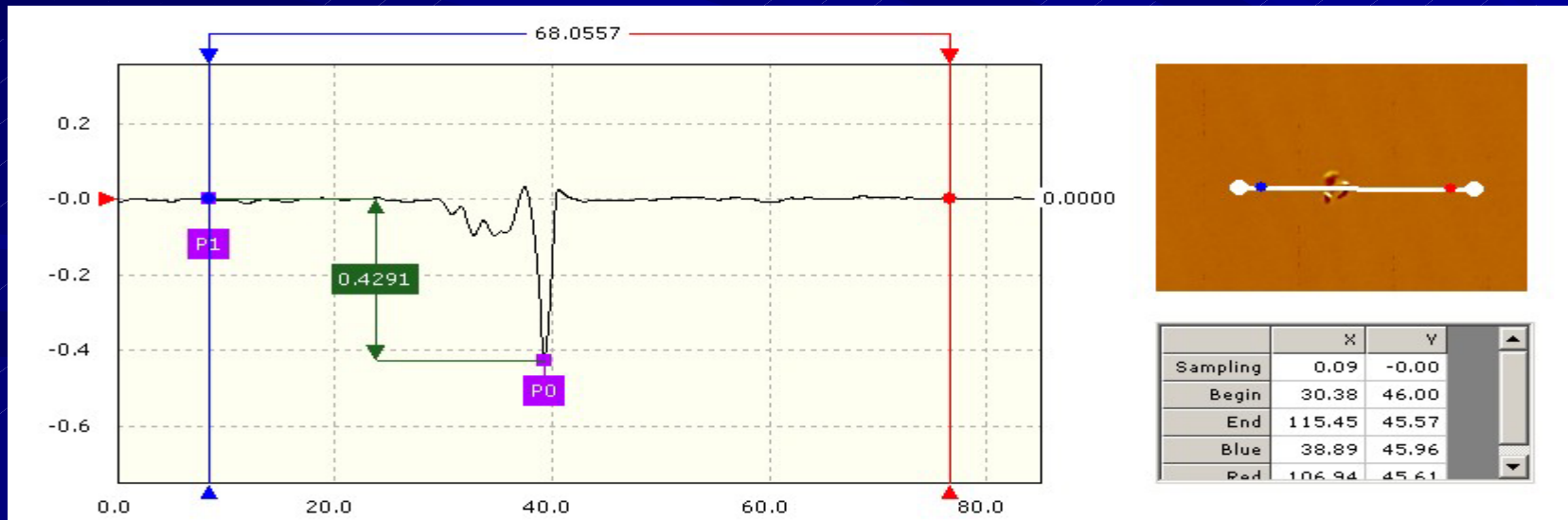


PT2 Tip Scrub Depth

O.D:3.5 mil

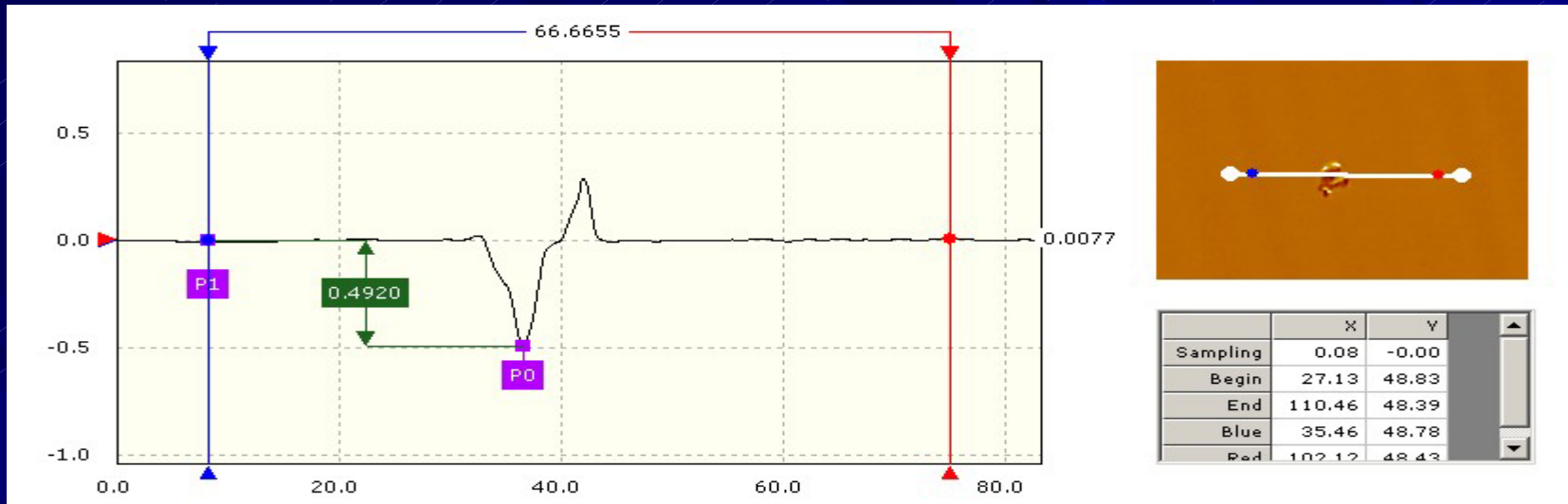


O.D:4.0 mil

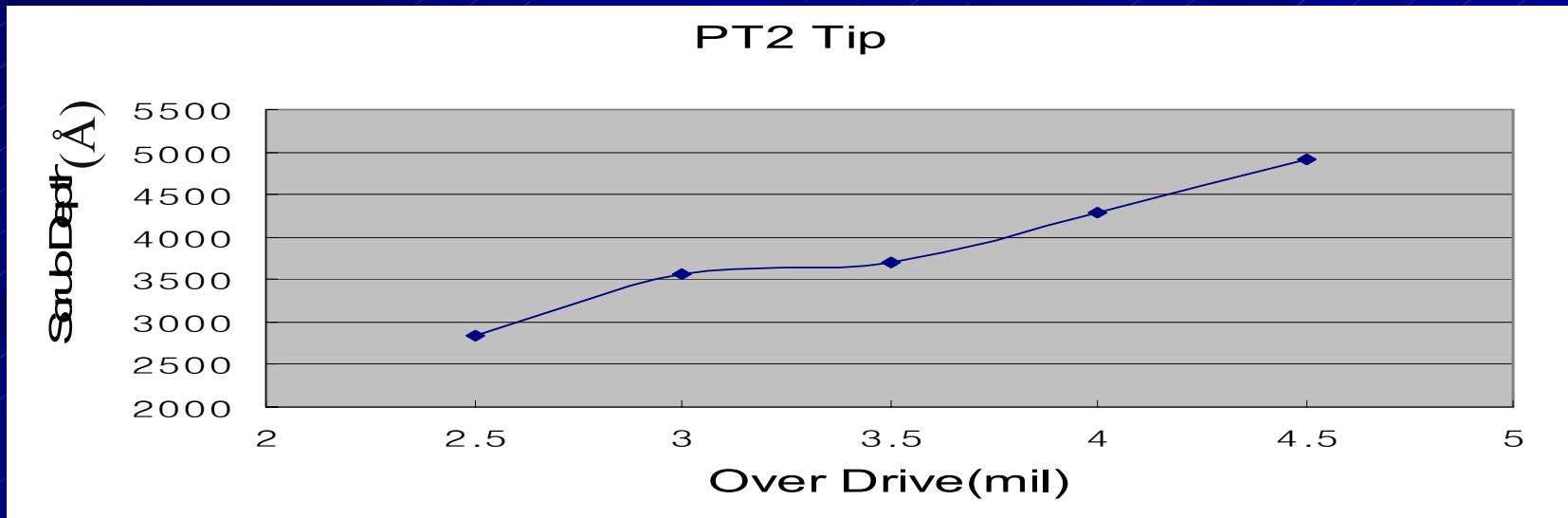


PT2 Tip Scrub Depth

O.D:4.5 mil

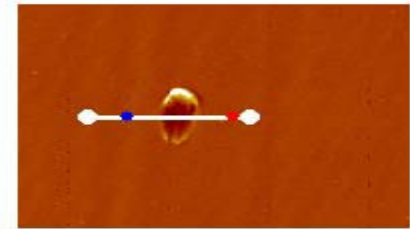
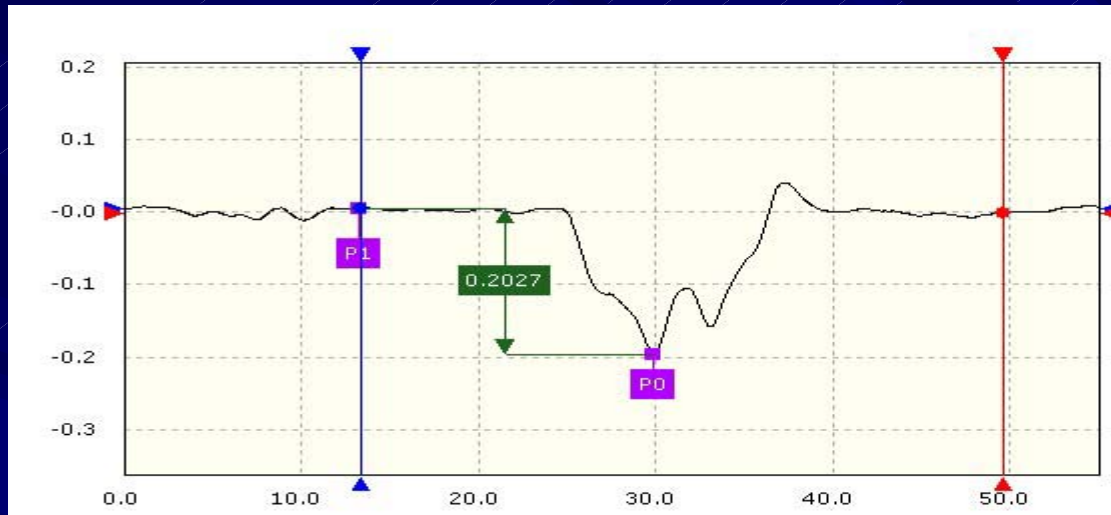


PT2 Tip Scrub Depth Trend



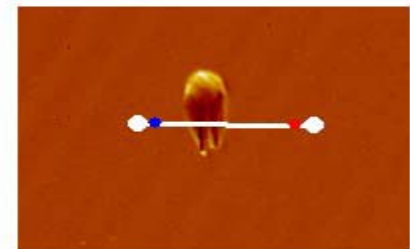
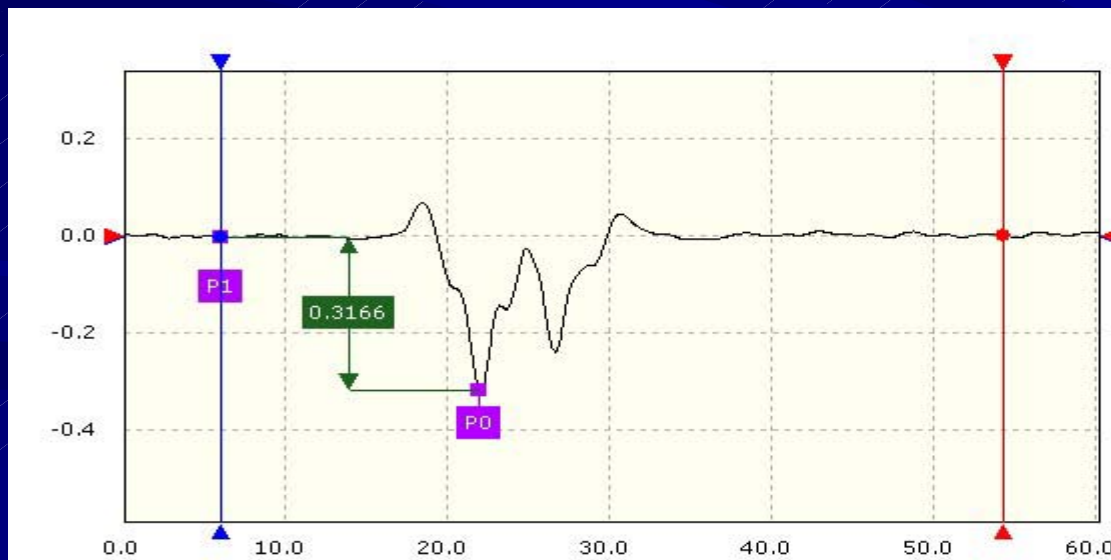
Needle Scrub Depth

O.D:2.5 mil



	X	Y
Sampling	0.06	0.00
Begin	24.31	50.56
End	79.43	50.56
Blue	37.63	50.56
Red	73.91	50.56

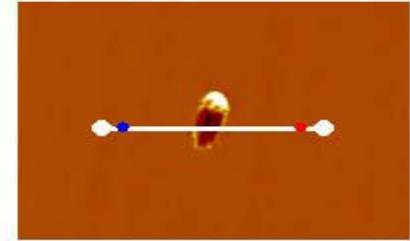
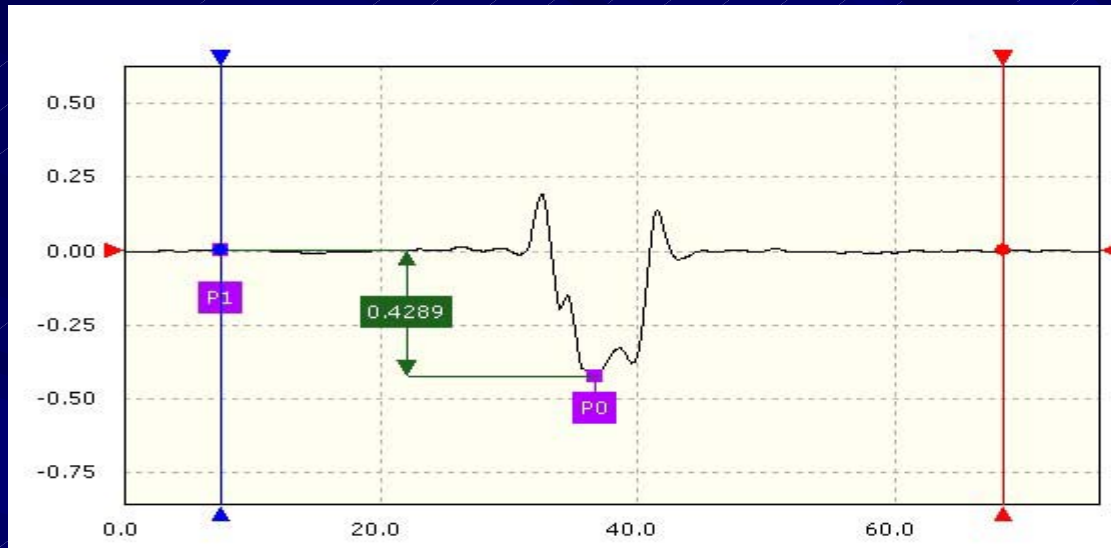
O.D:3.0 mil



	X	Y
Sampling	0.06	-0.00
Begin	41.23	52.95
End	101.56	52.51
Blue	47.26	52.91
Red	95.53	52.56

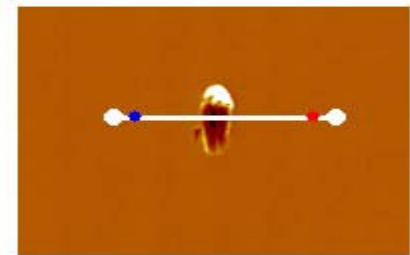
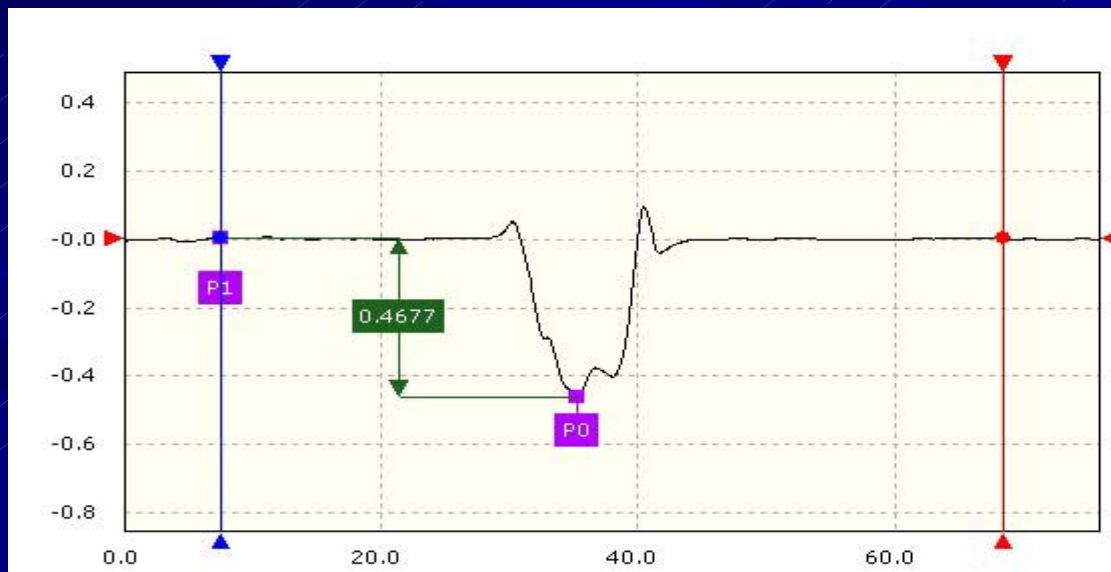
Needle Scrub Depth

O.D:3.5 mil



	X	Y
Sampling	0.08	0.00
Begin	28.86	47.31
End	104.82	47.31
Blue	36.46	47.31
Red	97.22	47.31

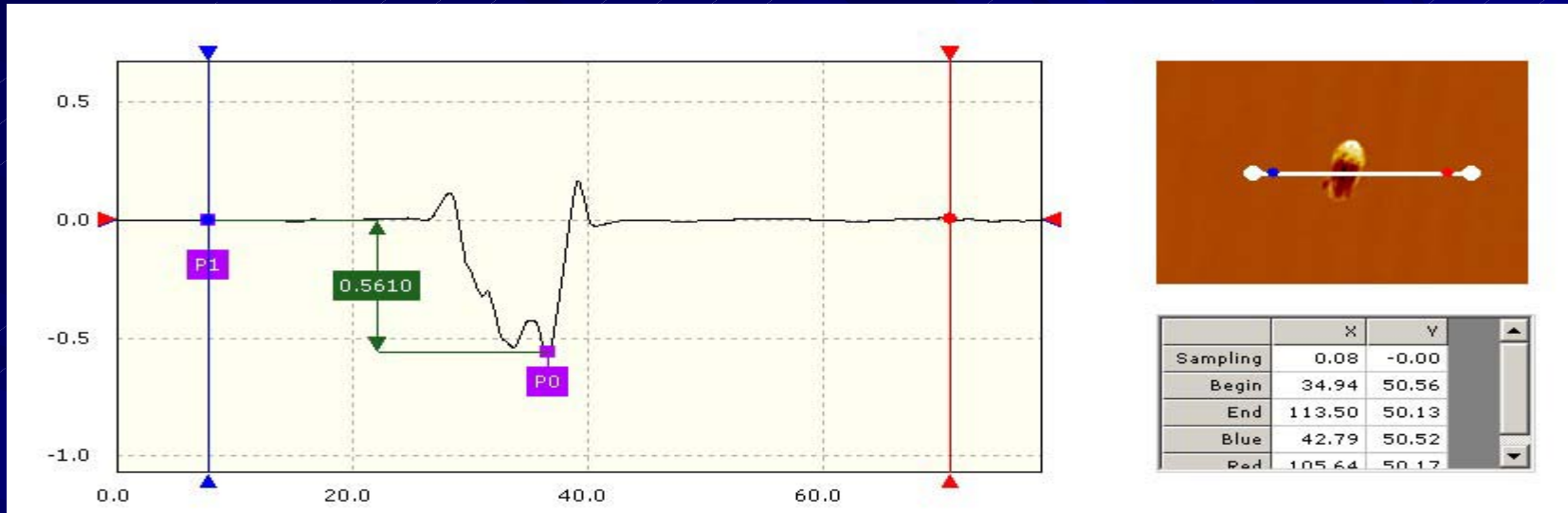
O.D:4.0 mil



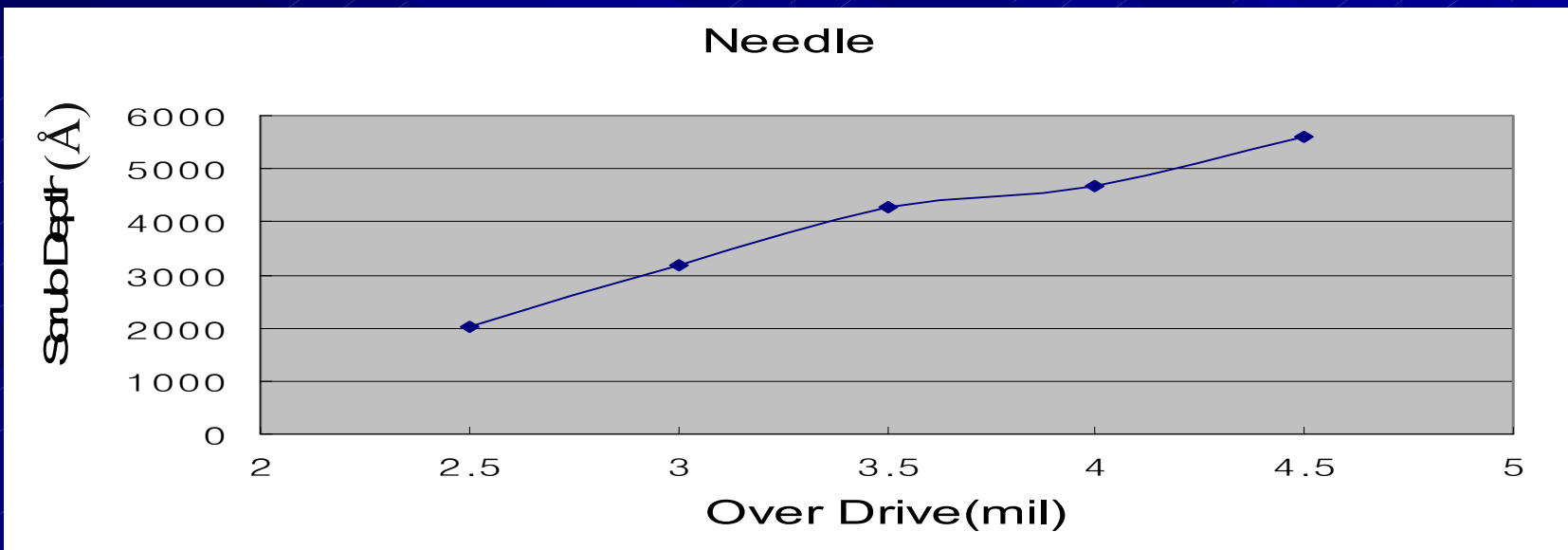
	X	Y
Sampling	0.08	-0.00
Begin	32.99	56.64
End	108.94	56.20
Blue	40.58	56.59
Red	101.34	56.25

Needle Scrub Depth

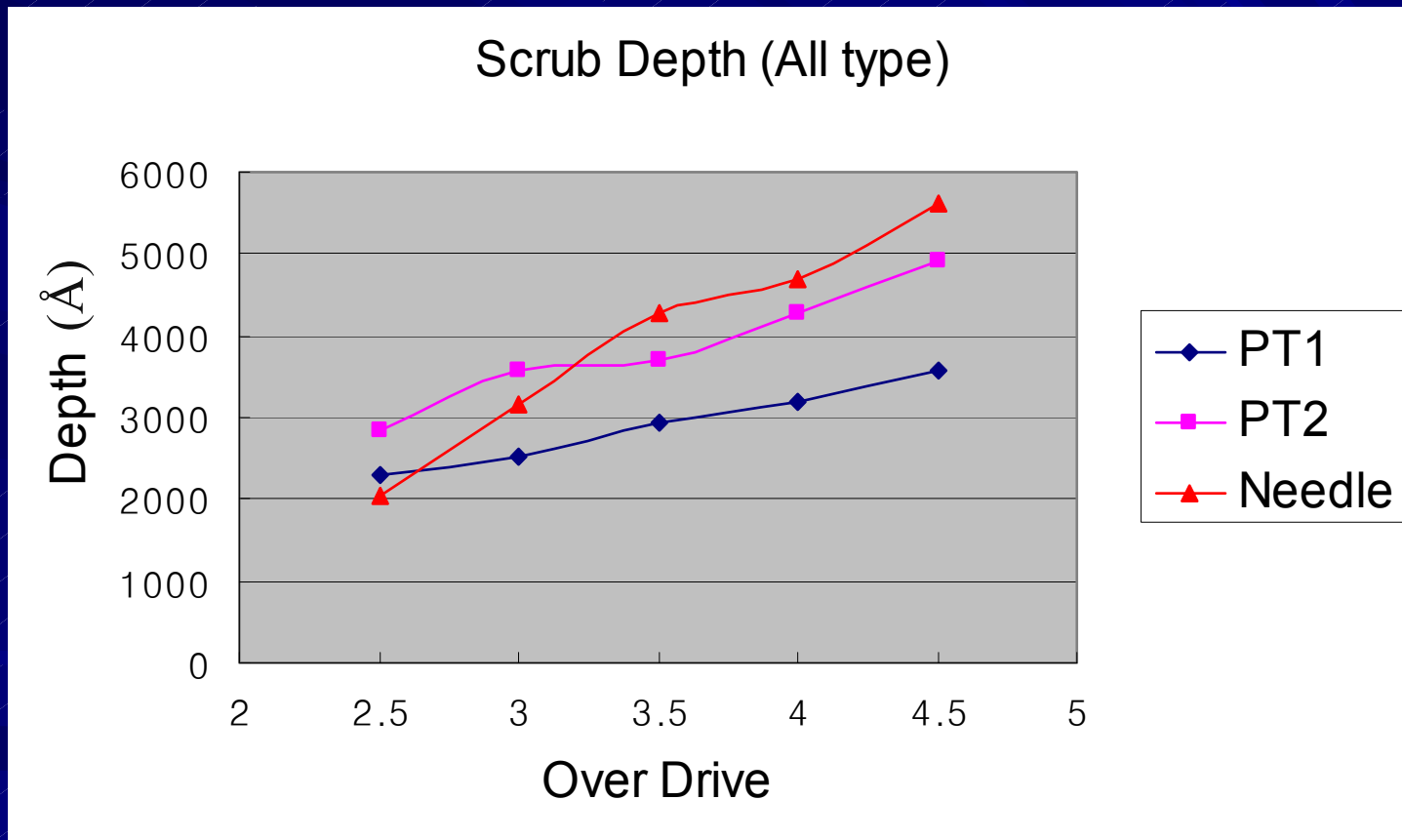
O.D:4.5 mil



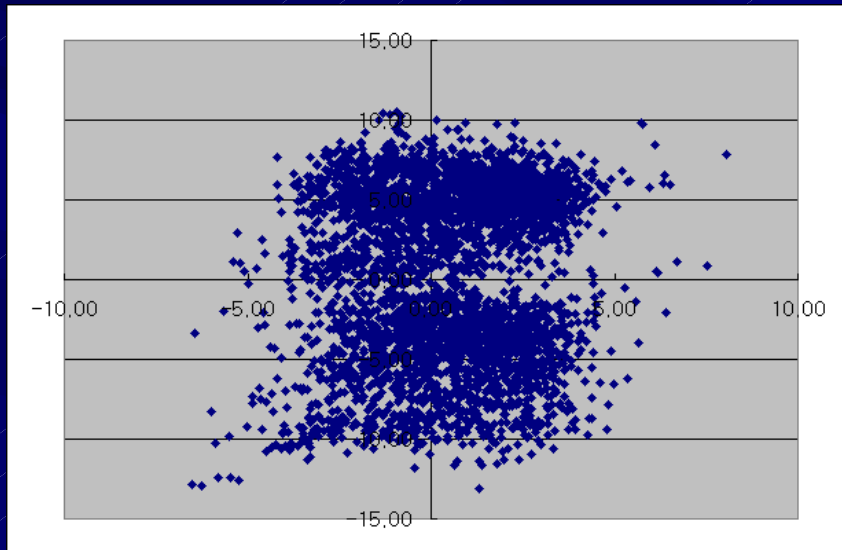
Needle Tip Scrub Depth Trend



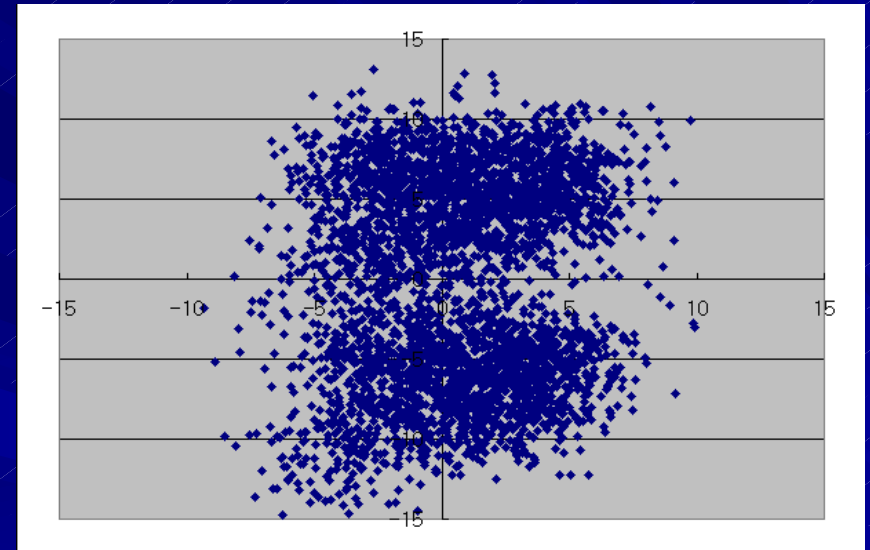
Scrub Depth (all types are compared)



5. Probe X,Y Alignment (MEMS)



Before TDS



After 29600 TDS

Real contact number on production line

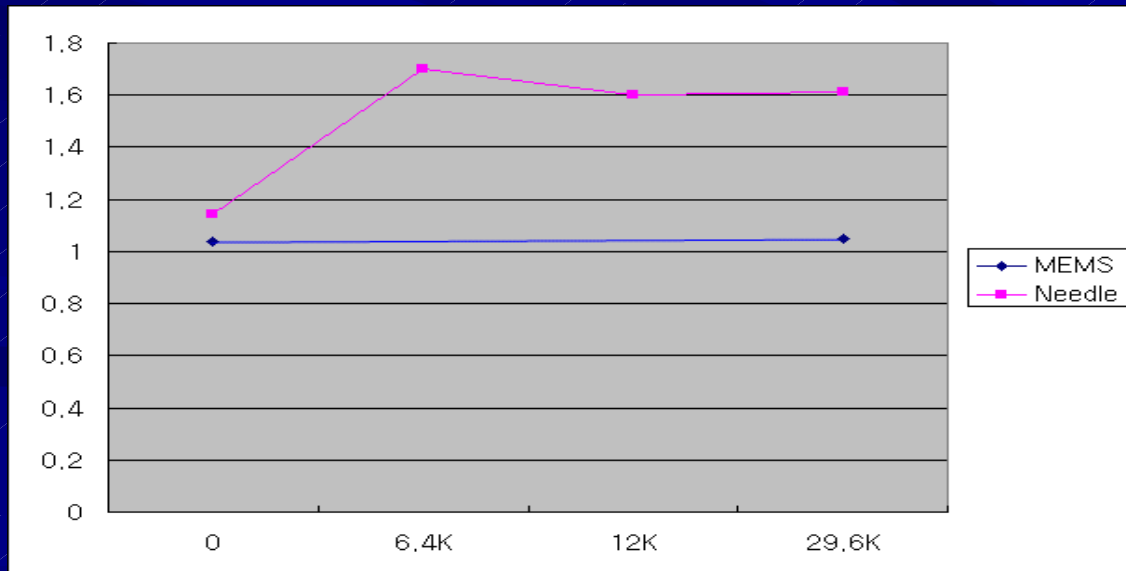
6. Path Resistance

- Touchdown Vs Path Resistance (Average)

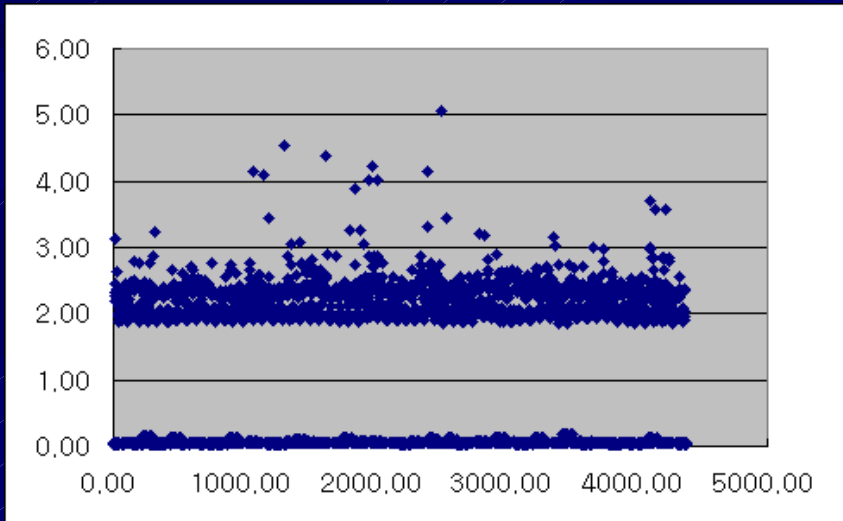
(Unit:Ohm)

TDS	0	6.4K	12K	29.6K
MEMS P/C	1.04			1.05
Needle P/C	1.1437	1.6981	1.6012	1.6121

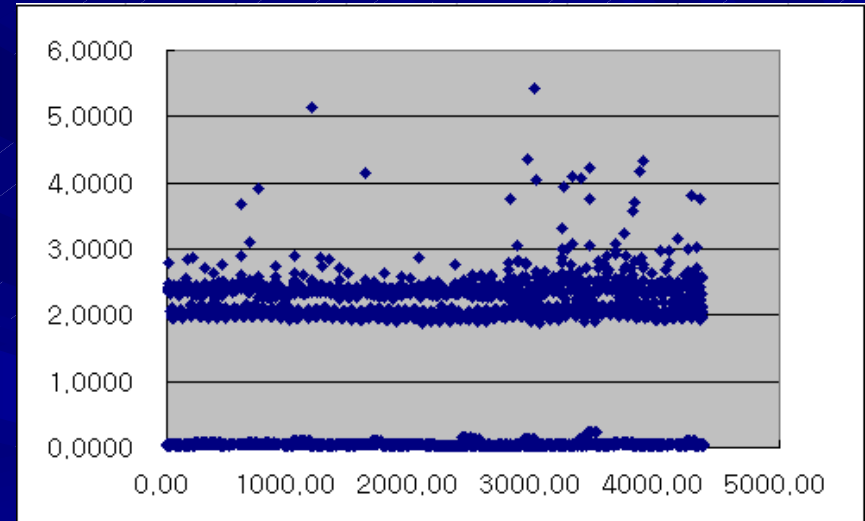
- Graph



MEMS P/C Path Resistance Trend



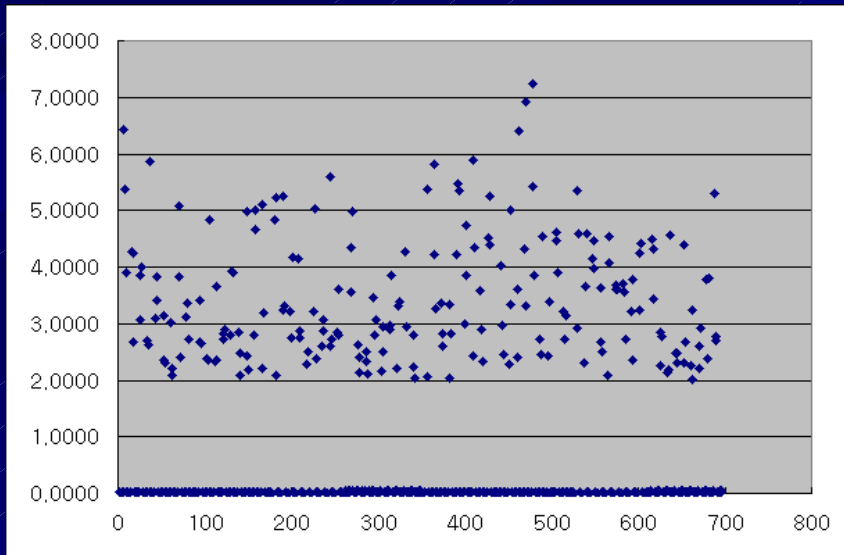
Before TDS



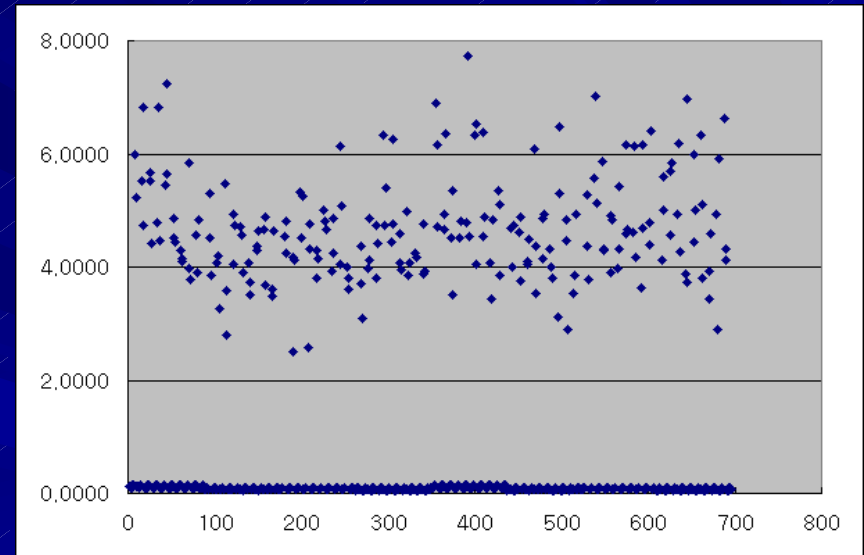
After 29600 TDS without Cleaning

Real contact number on production line

Needle P/C Path Resistance Trend



Before TDS



After 29600 TDS without Cleaning

Phicom Test Data

7. Probe Life Time

- Life Time (Number of Touchdowns)



32,000TDS



64,000TDS



120,000TDS

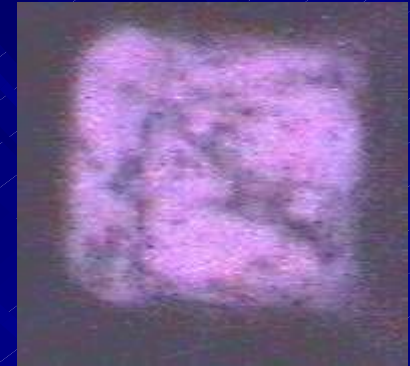
- Cleaning Period



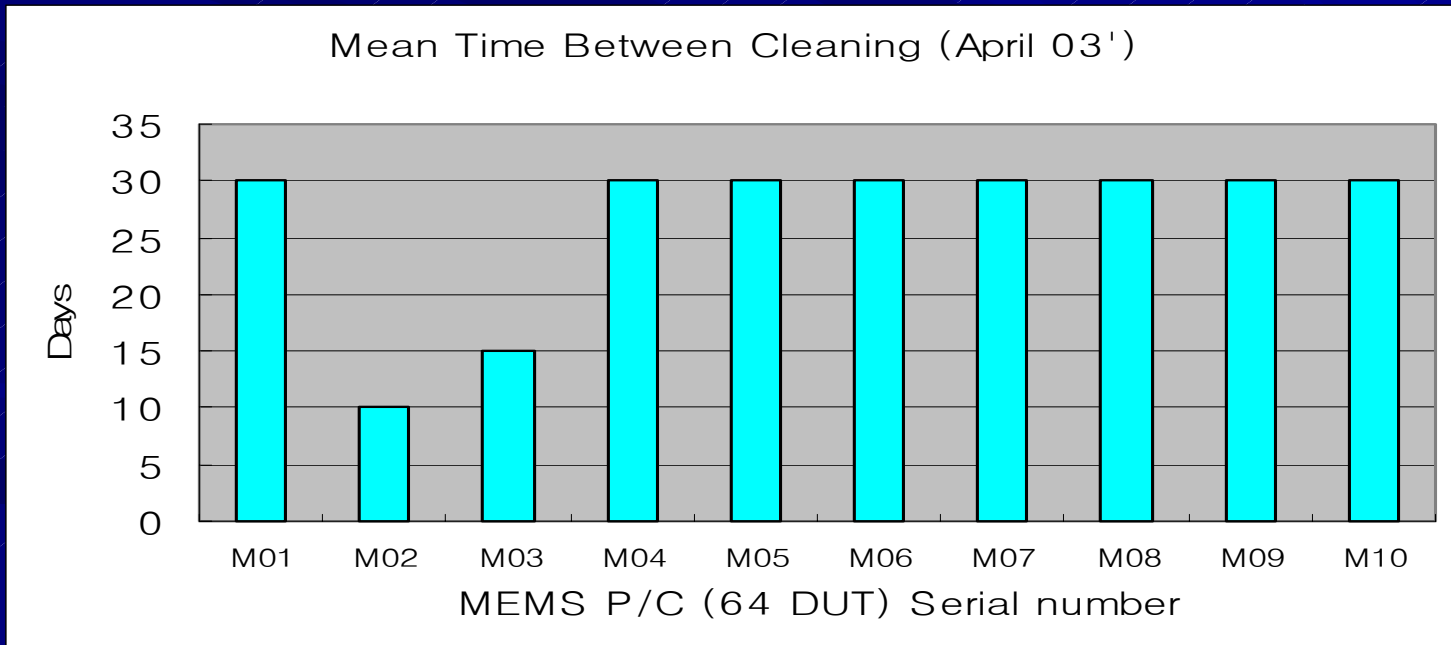
Initial



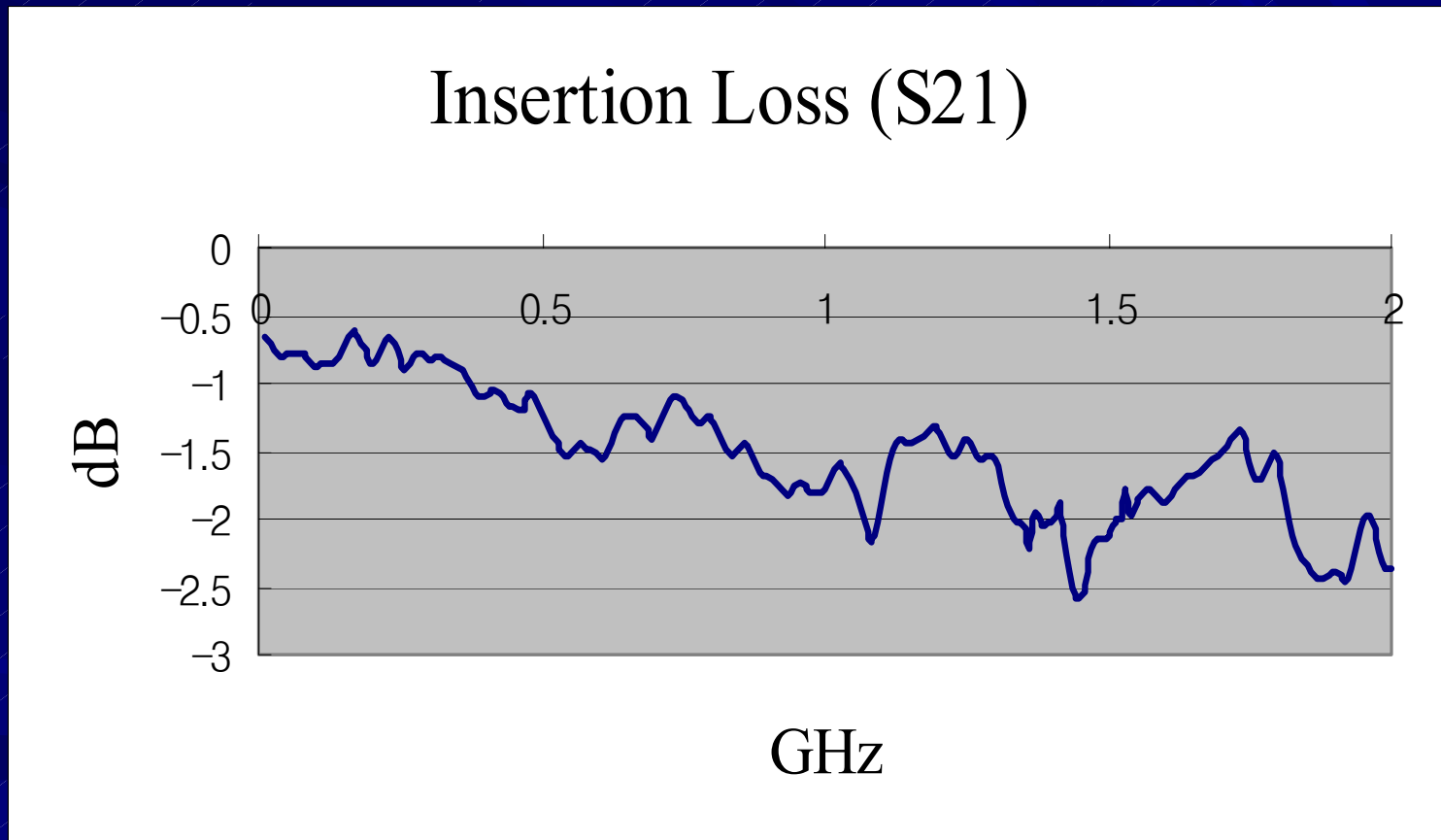
30000TDS



Cleaning



8. MEMS Probe Card Bandwidth



9. MEMS Probe Card Specification

Measurement Items		Specification		
		System	Value	Unit
Planarity		3D	15 ~ 20	um
			25 ~ 30	um
Leakage			<5	nA
Contact Resistance			<5	Ohm
Vxerr		PRVX	80 overlay	%
Vyerr			80 overlay	%
Scrub			10	um
Tscrub			25	um
Diameter			<18	um
Tip Diameter (Changeable)		SEM	< 13	um
Scrub Area (Based on O.D 75um)			<13x24	um ²
O.D.	Normal		75	um
	Maximum		110	um
Impedance		Polar	50 (±10%)	Ohm
Max Current			600	mA
Pin Force			2.5(±20%)	gf/mil
Probe Depth			8.8	mm
Cleaning Period			> 15,000	TDs
Life Time		Prober	1 Million	TDs

Summary

- **Enough Pin Force to penetrate Al₂O₃**
- **Stable Planarity**
- **Stable X.Y Alignment Status**
- **Low Pad Damage With Enough Scrub Mark**
- **Constant Path Resistance**
- **Long Cleaning Period**
- **Long Life Time**
- **Uniform Probe Tip Shape**